

# $V_3Si$ thin film deposition at Daresbury Laboratory.

WP9 meeting

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# Overview

- As expected from an A15 superconducting material,  $V_3Si$  has a relatively high critical temperature,  $T_c$ , of  $\sim 17.2$  K. Similar expectation to  $Nb_3Sn$ .
- Previous work has various methods of thin film production of  $V_3Si$ :
  - Diffusion of Si into Bulk V <sup>1</sup>
  - Co-sputtering and single target sputtering using magnetron sources<sup>2</sup>
  - HiPIMS <sup>3</sup>
- We have started with Pulsed DC magnetron sputtering of single alloy target.

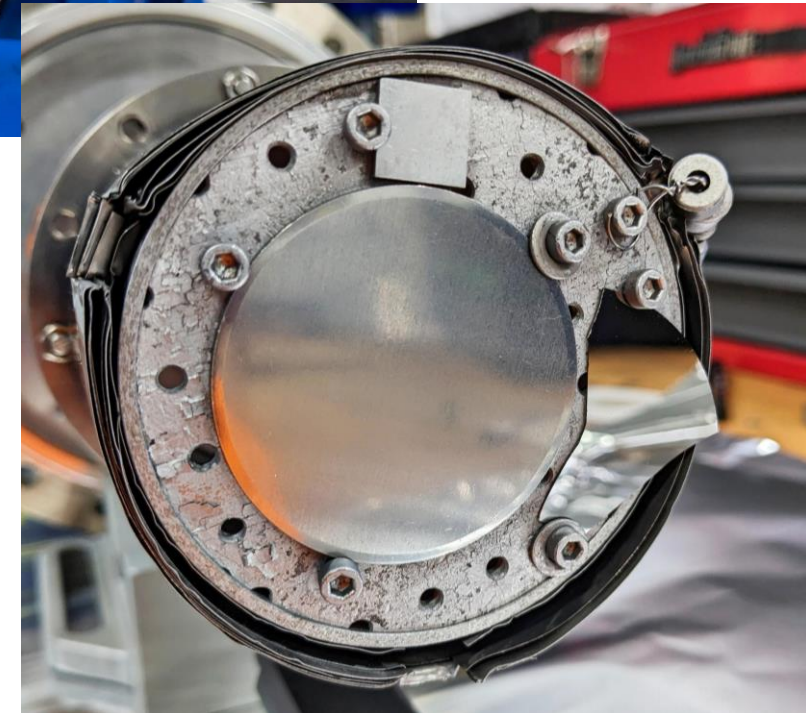
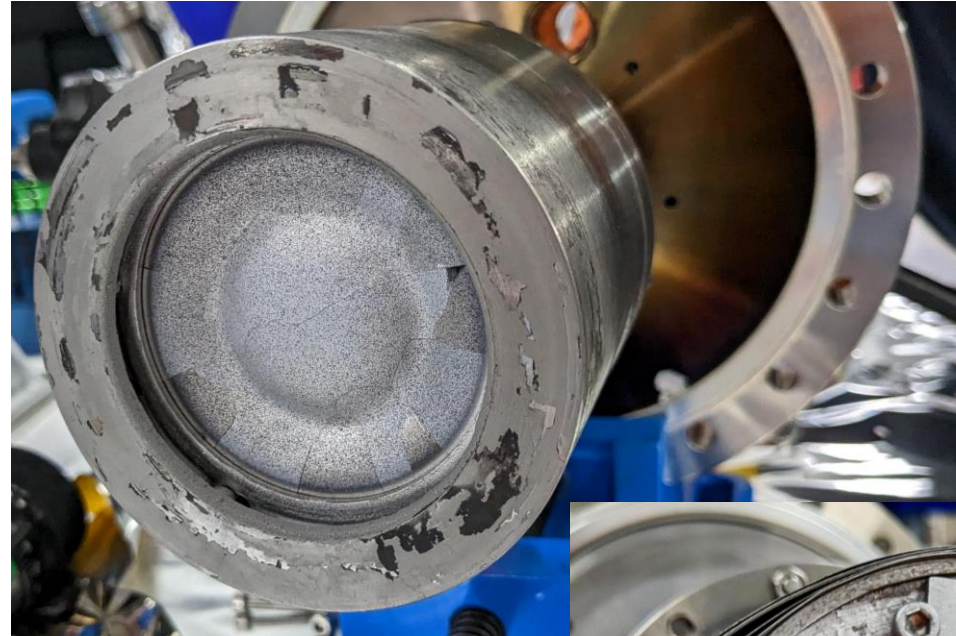
<sup>1</sup>S. M. Deambrosis. Proc. SRF '07. WE203.

<sup>2</sup>K. Howard, arXiv: 2031.00756, 2023

<sup>3</sup>F. L. Estrin, *9th Int. Workshop on Thin Films and New Ideas for Pushing the Limits of RF Superconductivity*, Poster 2021

# Deposition system

- System is equipped with a single planar magnetron source ( $V_3Si$  alloy target).
- Sample holder capable of heating to 800 C.
- Kr as the process gas.
- Base pressure  $5 \times 10^{-9}$  mbar



# Deposition 1 –

- Pulsed DC magnetron sputtering.

- Three samples:

10 x 10mm Cu piece

50 mm diameter Cu disk

Sapphire wafer

Surface analysis:

SEM/EDX

SIMS

XPS

DC magnetic field penetration  
measurements

[Liam Smith]

$T_c$  (Four point probe)

[Liam Smith]



Deposition parameters:

Substrate Temp: 790 C

Deposition length: 1:20:00

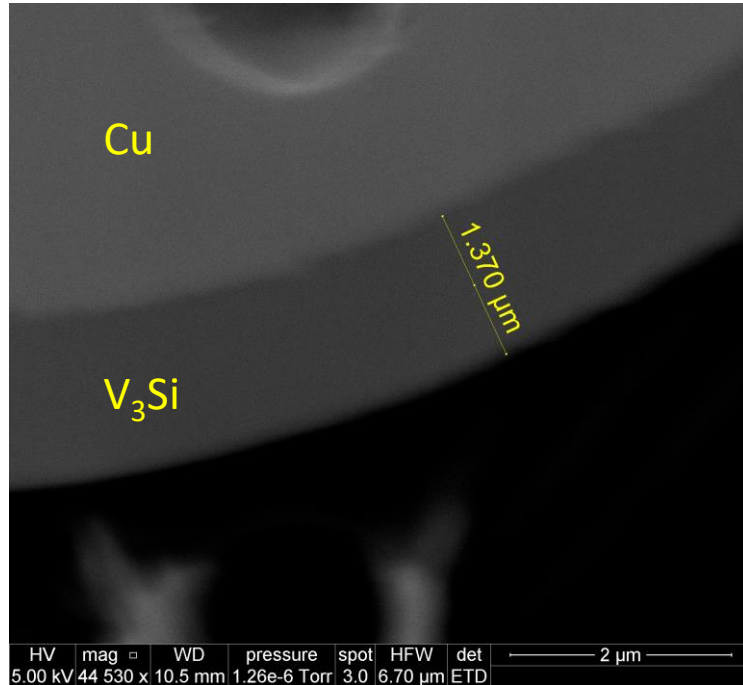
Pulse length: 1.1  $\mu$ s

Frequency: 350 kHz

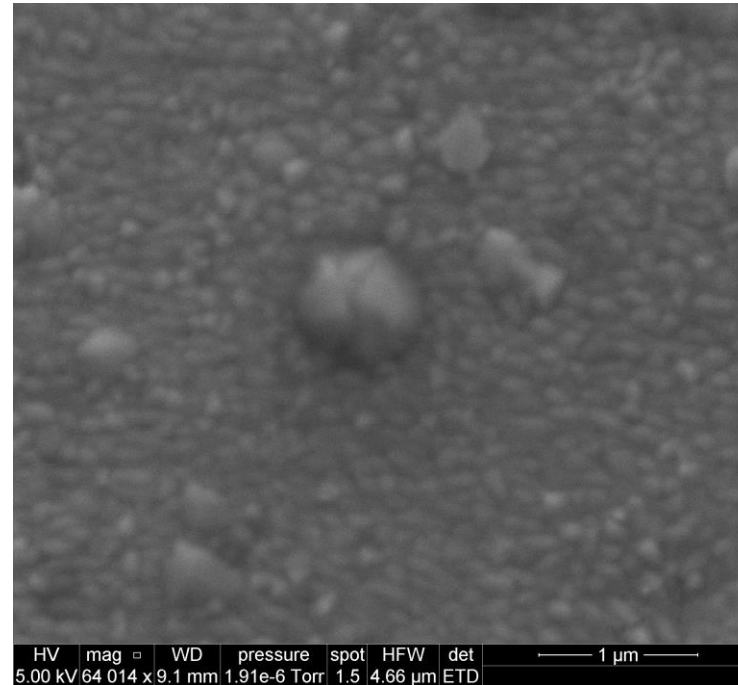
Power: 300 W

# Surface Characterisation: SEM/EDX

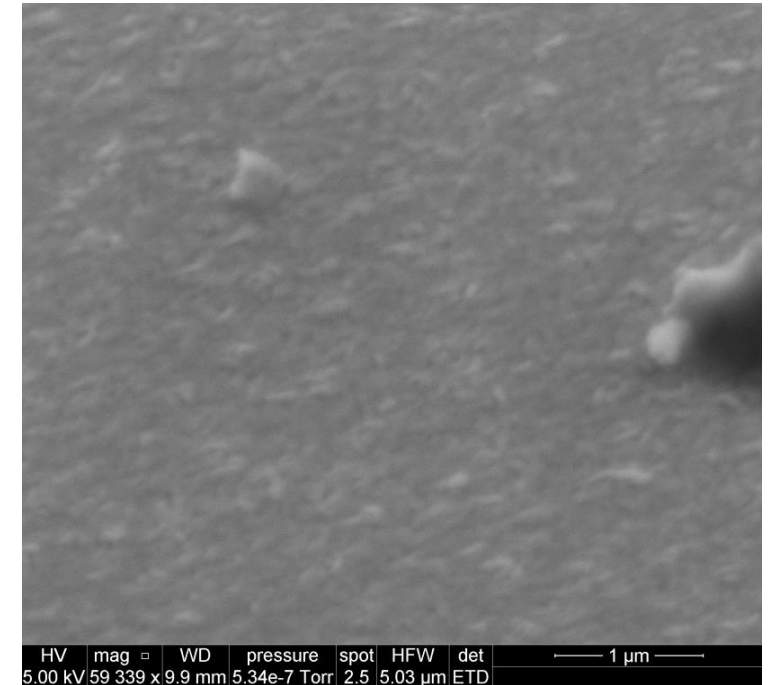
D1



$V_3Si$  cross section on Cu



$V_3Si$  on Cu morphology



$V_3Si$  on sapphire

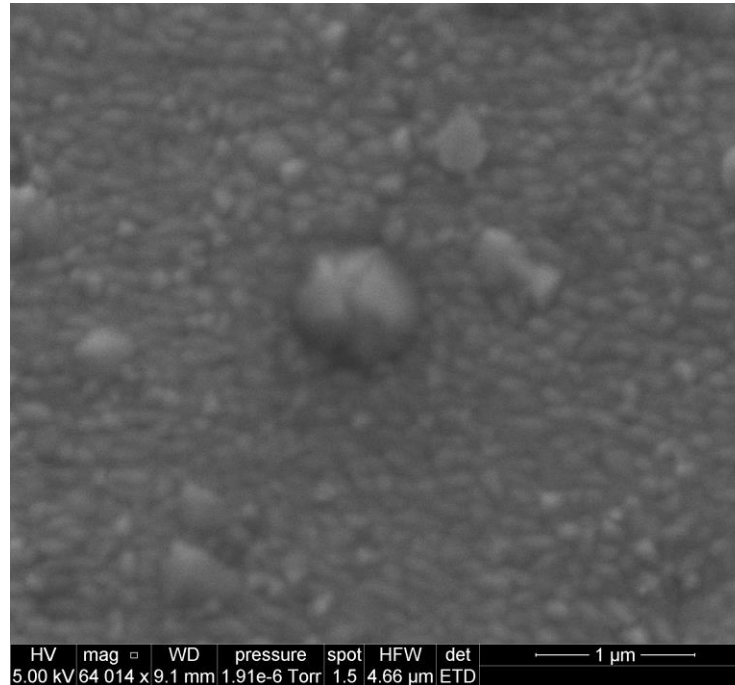
# Surface Characterisation: SEM/EDX

D1

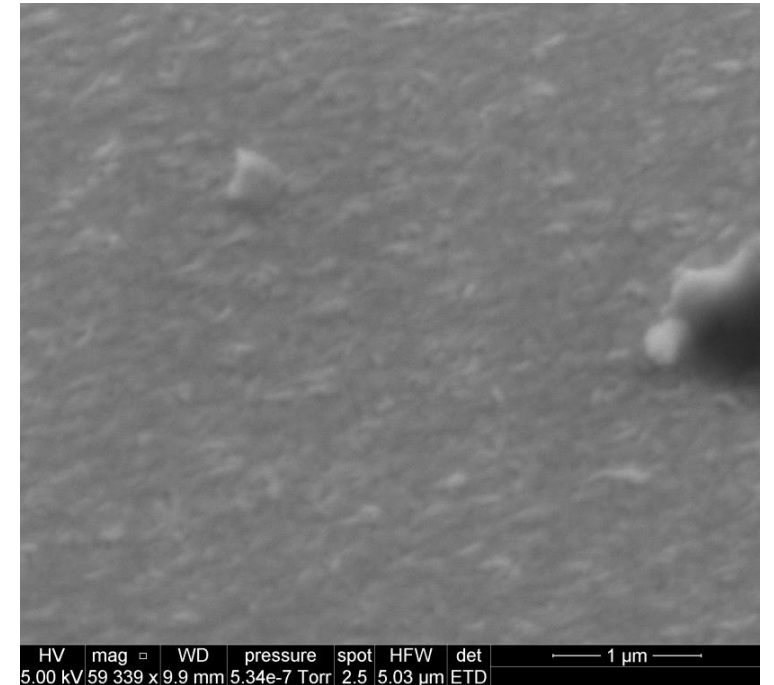
Energy dispersive x-ray spectroscopy:

Composition:

- V 72 %
- Si 28 %
  
- Slightly silicon rich.



V<sub>3</sub>Si on Cu morphology



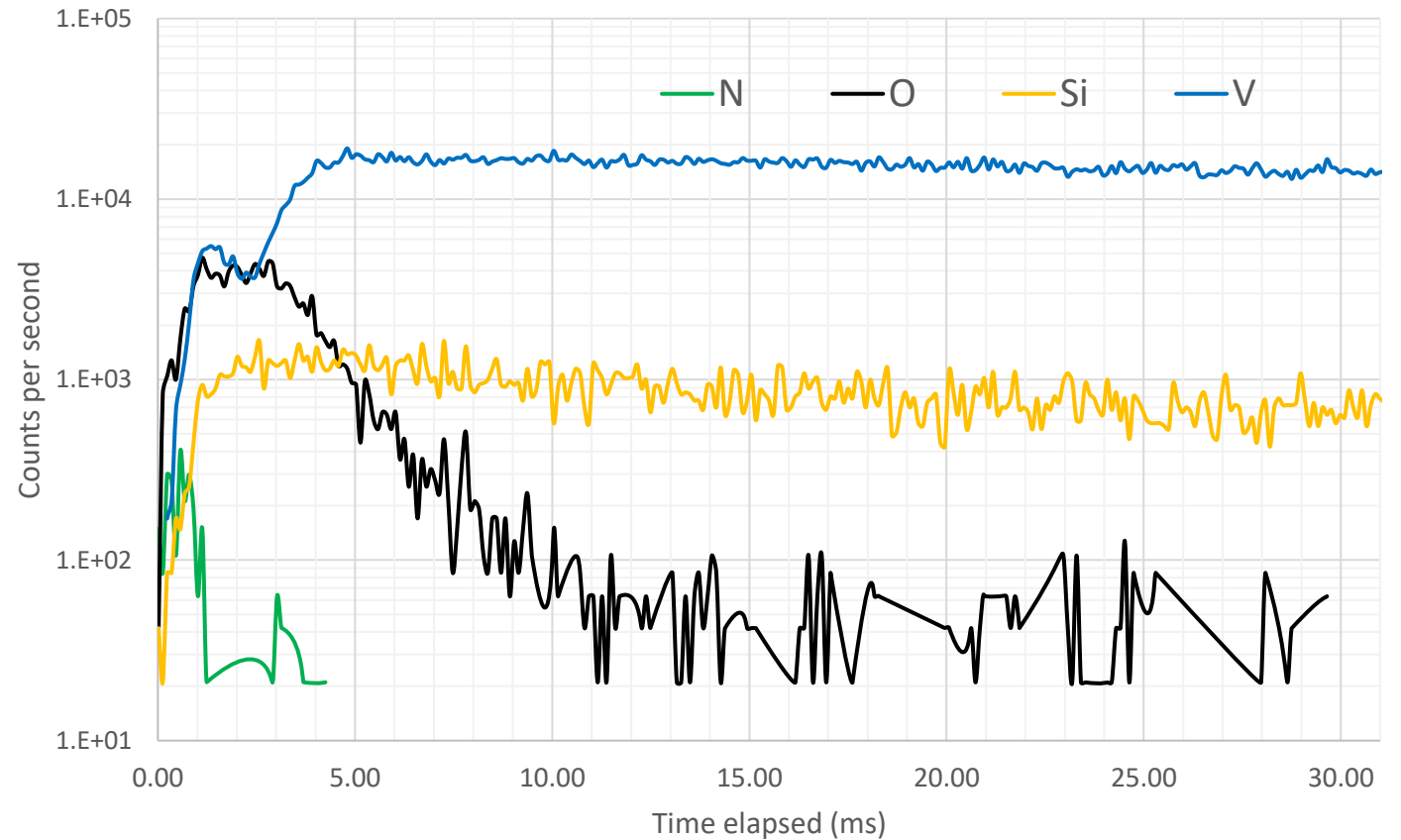
V<sub>3</sub>Si on sapphire

# Surface Characterisation: SIMS

D1

Last dataset taken on this sample set was Secondary Ion Mass Spectroscopy

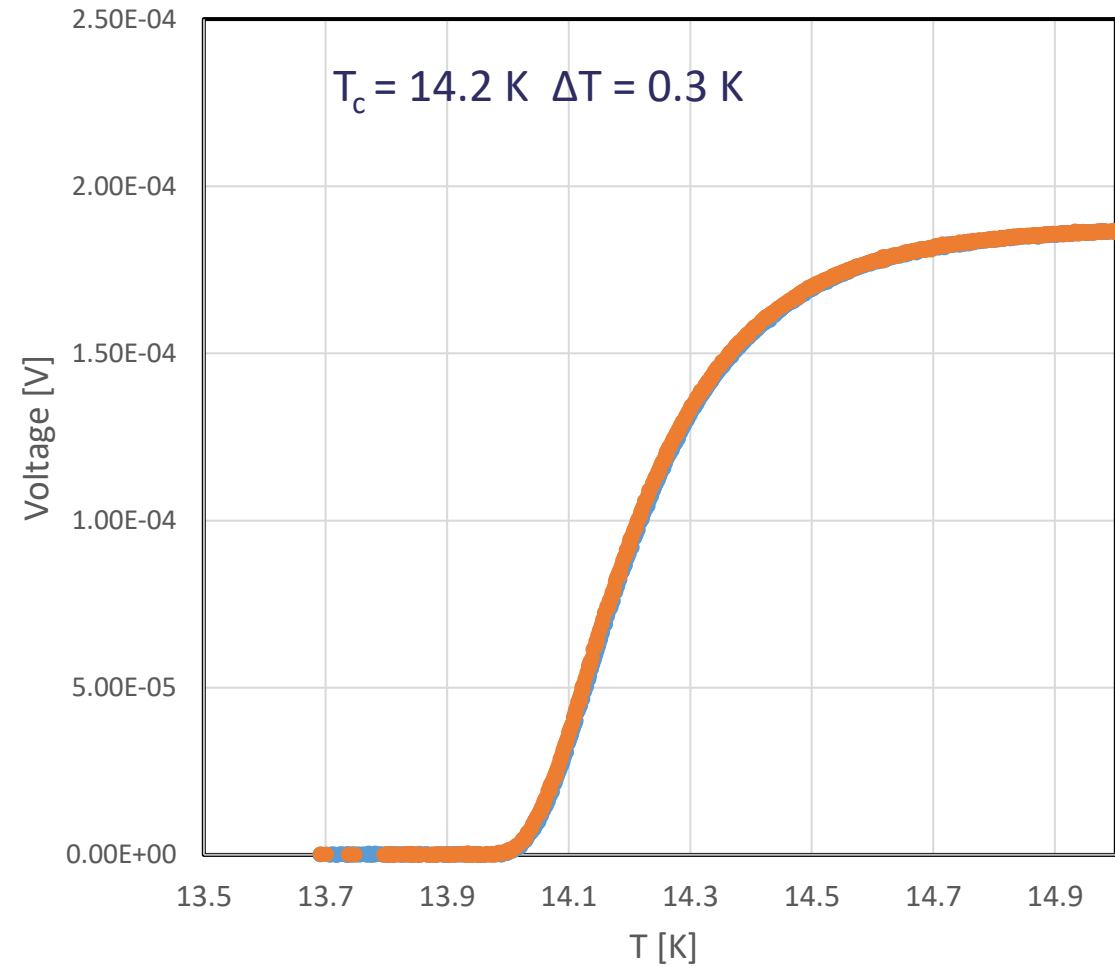
- We now have the capability to conduct SIMS measurements and will be introducing it as a final characterisation step. Depth profiling and checking for contamination through the bulk.
- A surface oxide layer present.
- A consistent V – Si layer throughout the Bulk



# $T_c$ Measurements

D1

- A measured  $T_c$  of 14.2 K on the sapphire sample using four point probe.





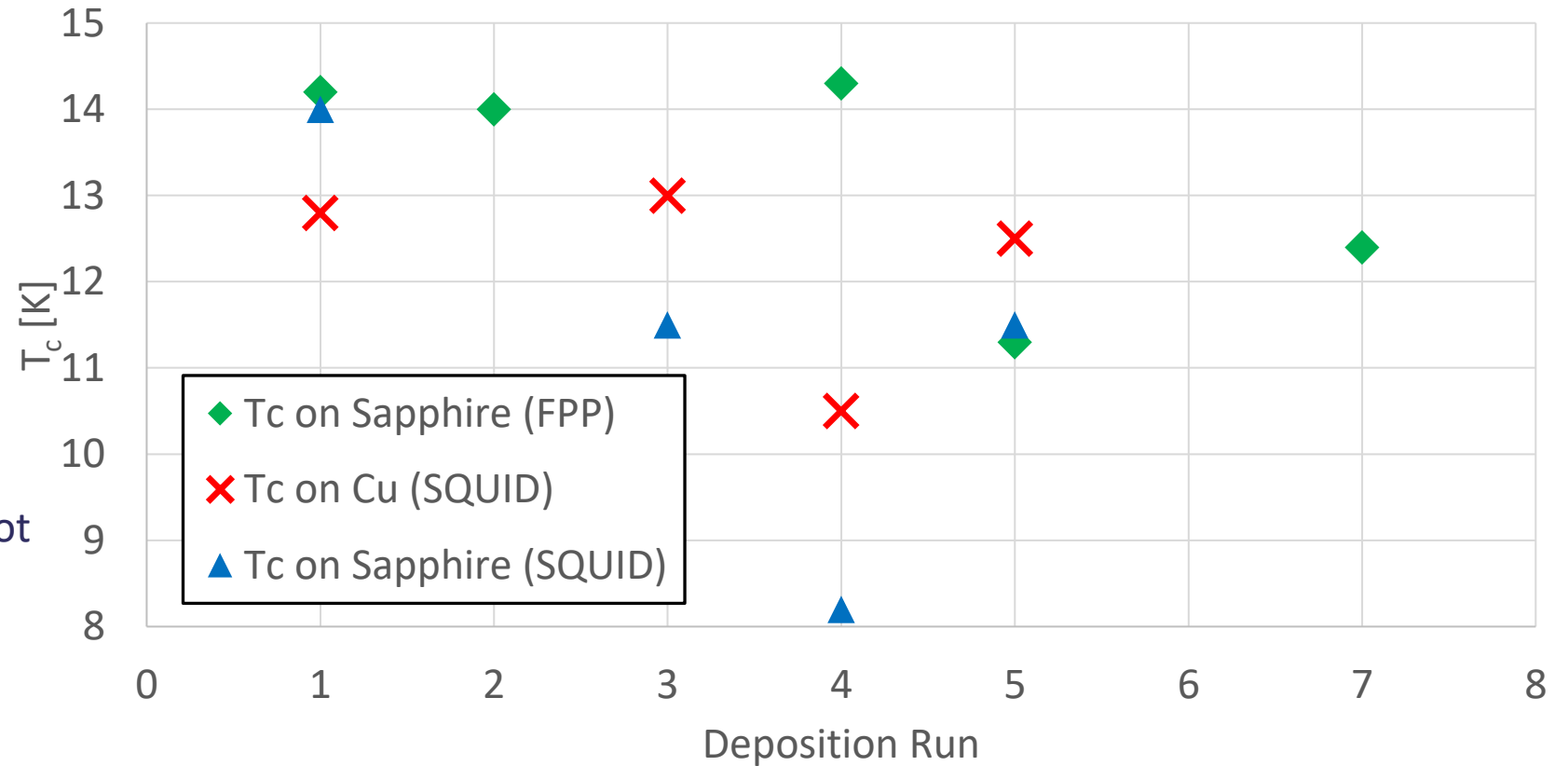
# Deposition Summary

- In total 10 depositions have been done with  $T_c$ 's measured for most sapphire substrates. A few samples were sent to Eugen Seiler For SQUID.

- Initial work was to investigate substrate temperature during deposition.

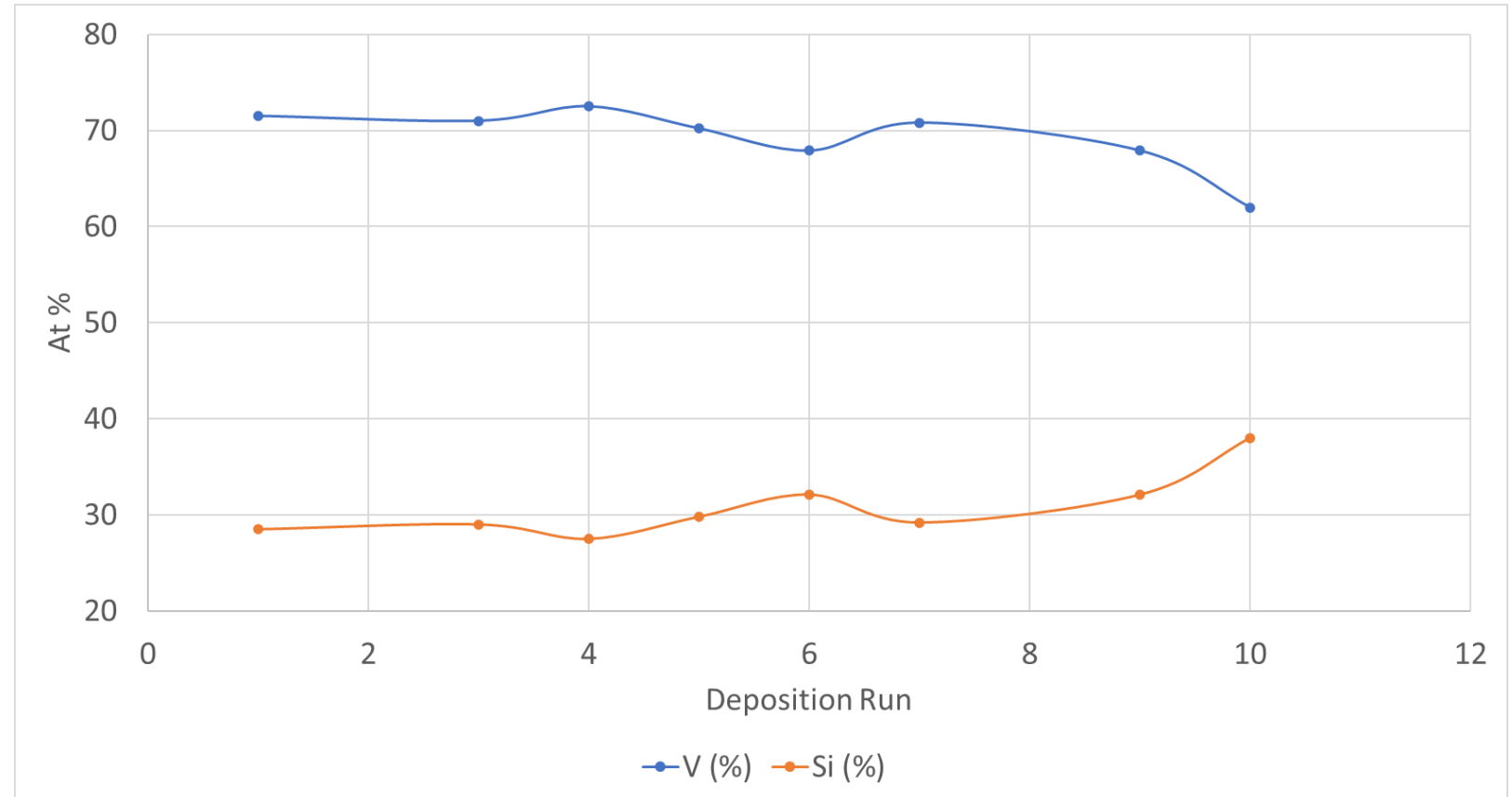
-  $T_c$  varied with no consistency in relation to substrate temperature.

- Last two depositions (9 and 10) repeated first deposition but were not superconducting.



# Composition variation

- Energy dispersive x-ray analysis shows a change in composition over time.
- All samples Si rich but at% increasing over time.
- Resulting in later depositions definitely not the desired A15 phase.
- Target removed and replaced with a fresh one.



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# Next steps

- Full characterisation of surface and bulk can now be achieved with SIMS, SEM, XPS and EDX. In conjunction with superconducting testing facilities.
- A fresh  $V_3Si$  target has been loaded into the system. First set of depositions will investigate composition and reproducibility of the film.
- Investigation into substrate temperature, post-annealing and HiPIMS.
- Adapt the system to allow for the 100 mm diameter samples for the RF choke cavity system to measure surface resistance managed by Dan Seal.

# Thanks for listening

## Acknowledgements

STFC: Reza Valizadeh, Oleg Malyshev, Liam Smith, James Colon and Daniel Seal

Institute of Electrical Engineering SAS: Eugen Seiler for the SQUID measurements